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(12) **United States Design Patent**
Dispenza et al.

(10) **Patent No.:** **US D723,395 S**
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- (54) **SENSOR HOUSING**
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- (73) Assignee: **FLIR Systems, Inc.**, Wilsonville, OR (US)
- (**) Term: **14 Years**
- (21) Appl. No.: **29/475,643**
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- (51) **LOC (10) Cl.** **10-04**
- (52) **U.S. Cl.**
USPC **D10/53; D16/203**
- (58) **Field of Classification Search**
CPC G01C 3/08; G02B 13/009; G02B 15/00; G03B 17/00; G03B 17/561; G03B 15/00; G03B 37/10; G08B 13/19619; G08B 13/1963; G08B 13/19697; G08B 17/00; H04N 5/2251; H04N 5/23296; H04N 5/247; H04N 5/33; H04N 5/2254; H04N 5/2252
USPC D10/52, 53; D16/200, 202–204, D16/208–210; 348/143, 151, 373–376; 358/909.1; 396/535–541, 427
See application file for complete search history.

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(57) **CLAIM**

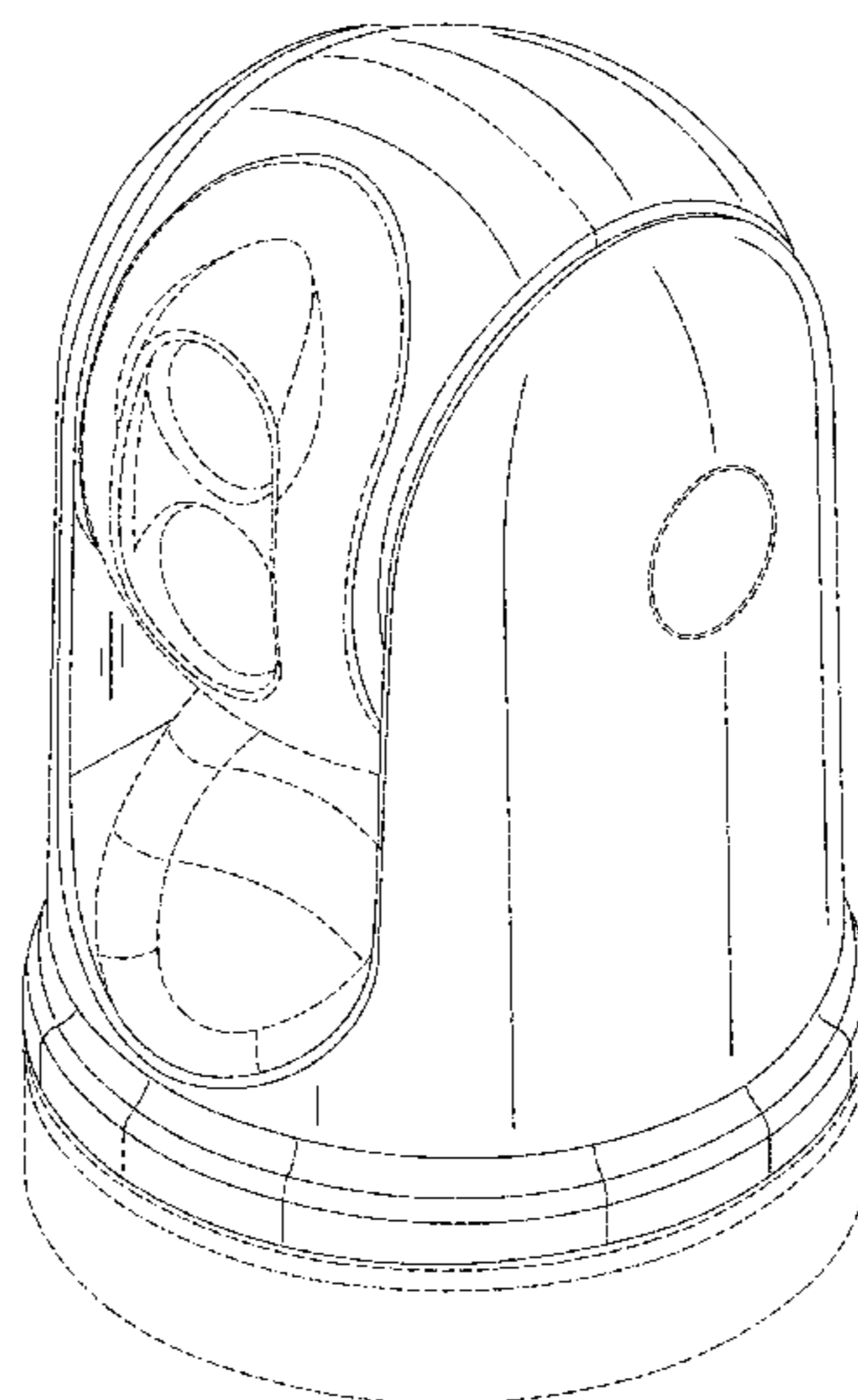
The ornamental design for a sensor housing, as shown and described.

DESCRIPTION

FIG. 1 is a front left top perspective view of a sensor housing showing our new design;
 FIG. 2 is a front elevational view thereof;
 FIG. 3 is a rear elevational view thereof;
 FIG. 4 is a right side elevational view thereof;
 FIG. 5 is a left side elevational view thereof;
 FIG. 6 is a top plan view thereof;
 FIG. 7 is a bottom plan view thereof;
 FIG. 8 is another front left top perspective view of the sensor housing showing our new design;
 FIG. 9 is a front elevational view thereof;
 FIG. 10 is a rear elevational view thereof;
 FIG. 11 is a right side elevational view thereof;
 FIG. 12 is a left side elevational view thereof;
 FIG. 13 is a top plan view thereof; and,
 FIG. 14 is a bottom plan view thereof.
 The broken lines shown in the drawings are for the purpose of illustrating environmental matter and/or illustrating portions of the sensor housing that form no part of the claimed design.

1 Claim, 14 Drawing Sheets

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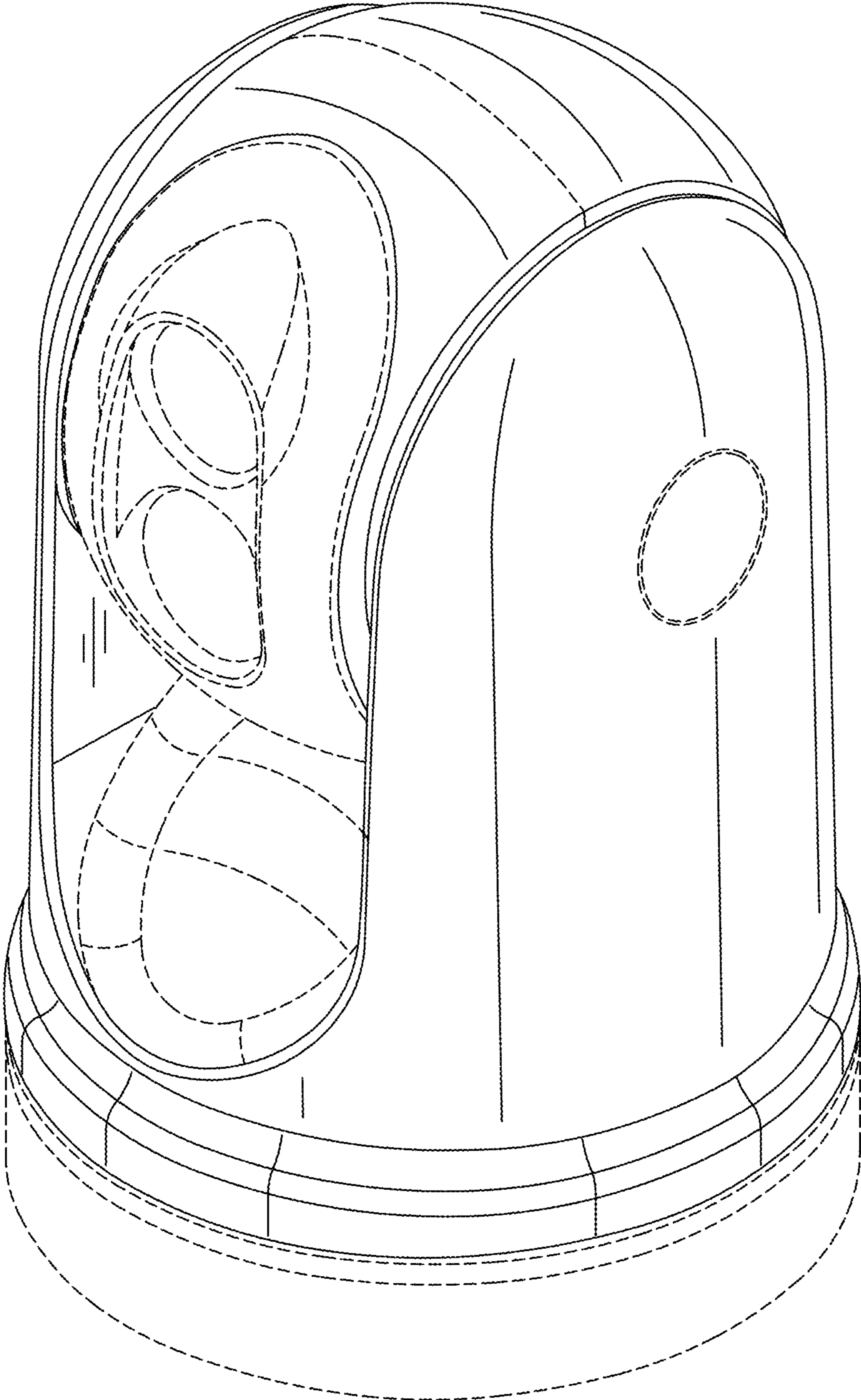


FIG. 1

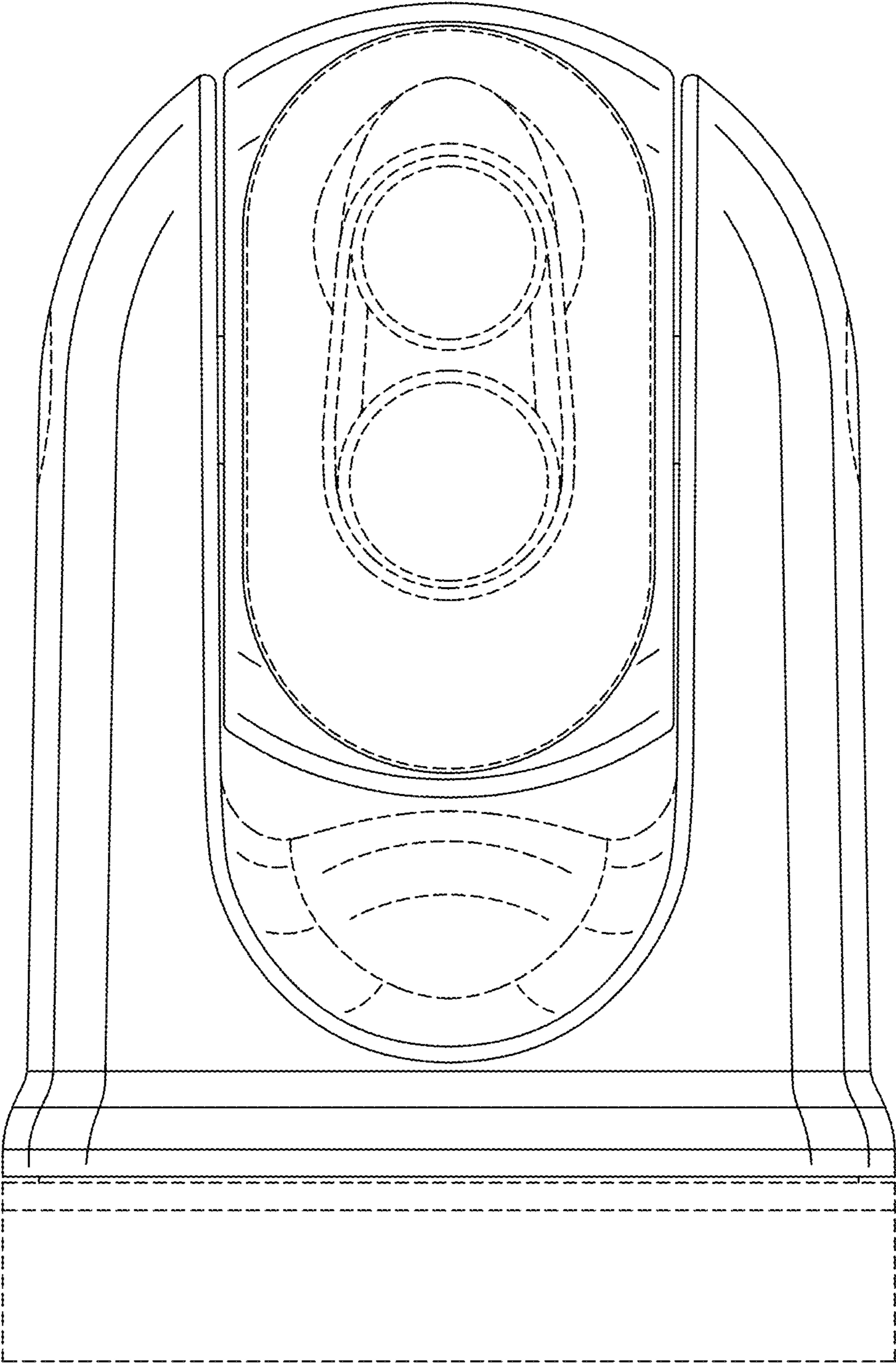


FIG. 2

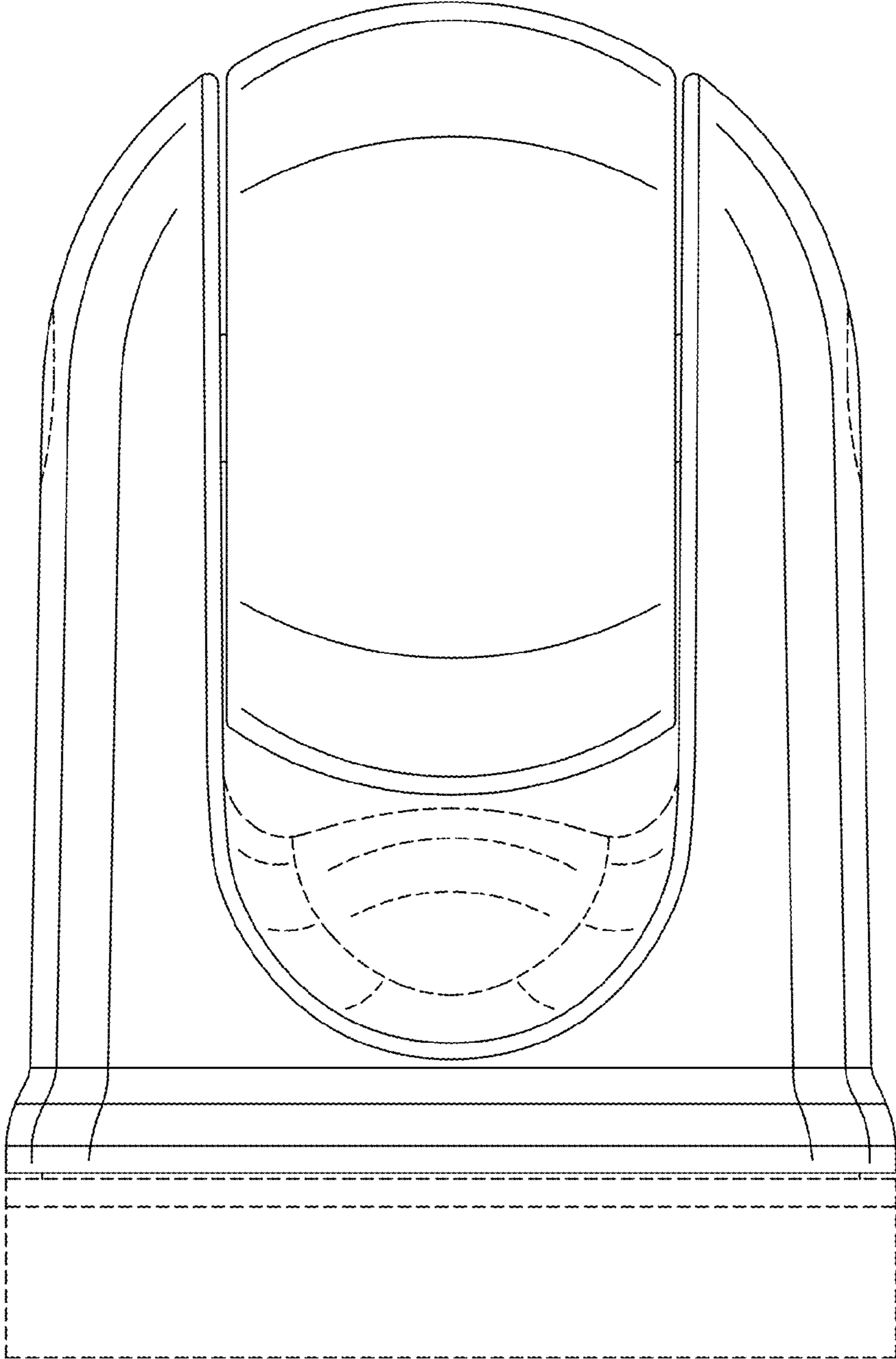


FIG. 3

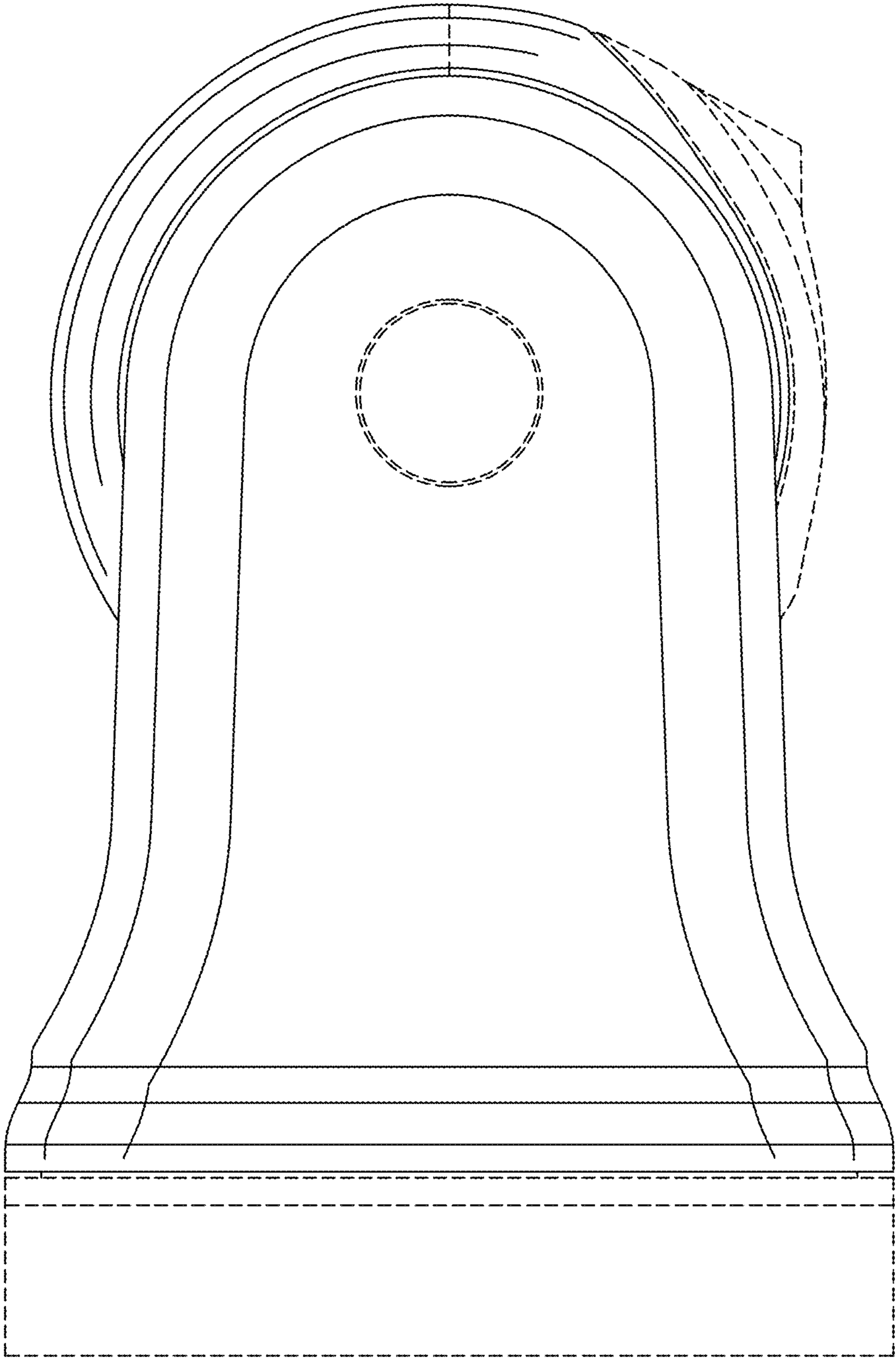


FIG. 4

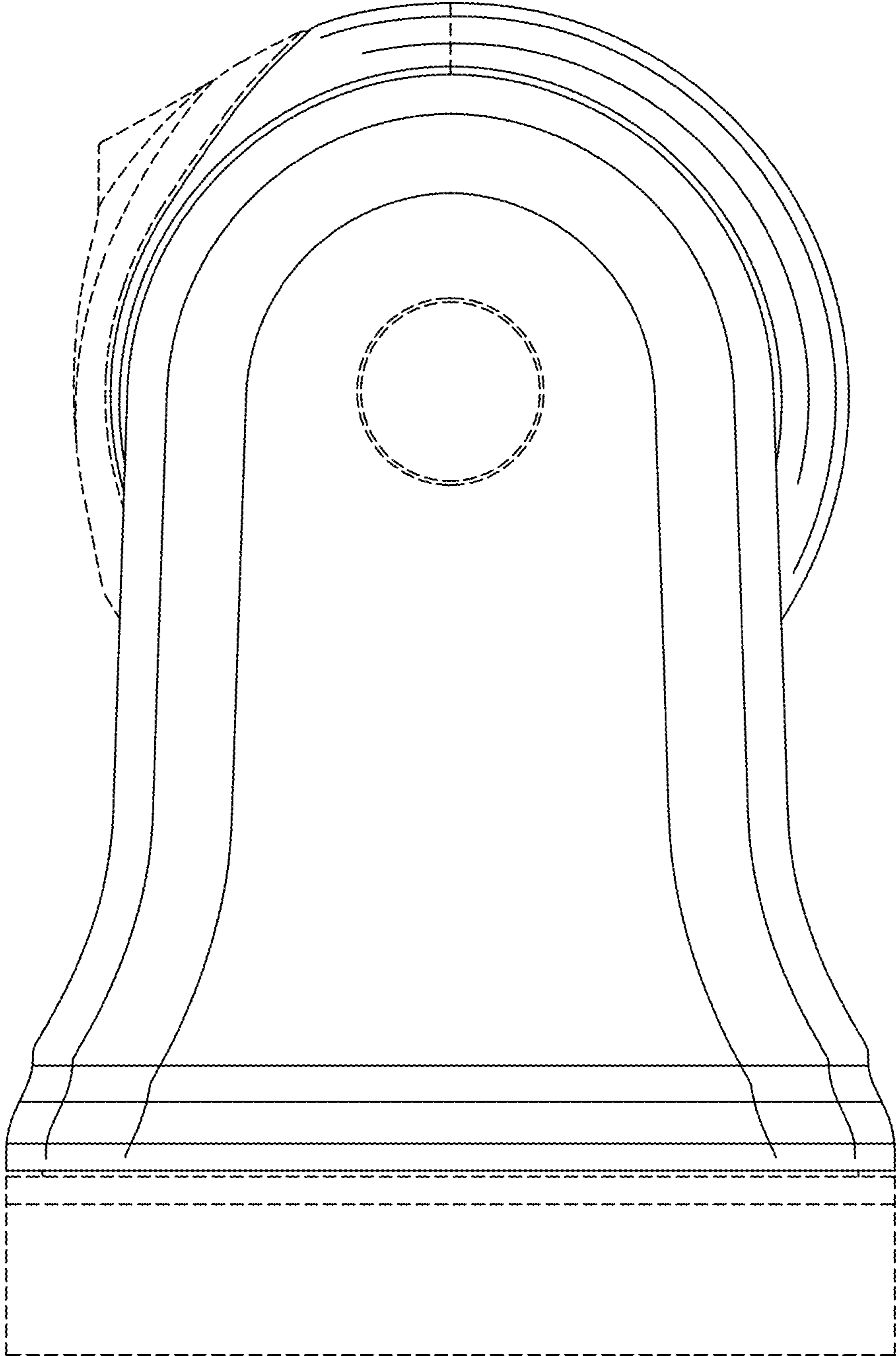


FIG. 5

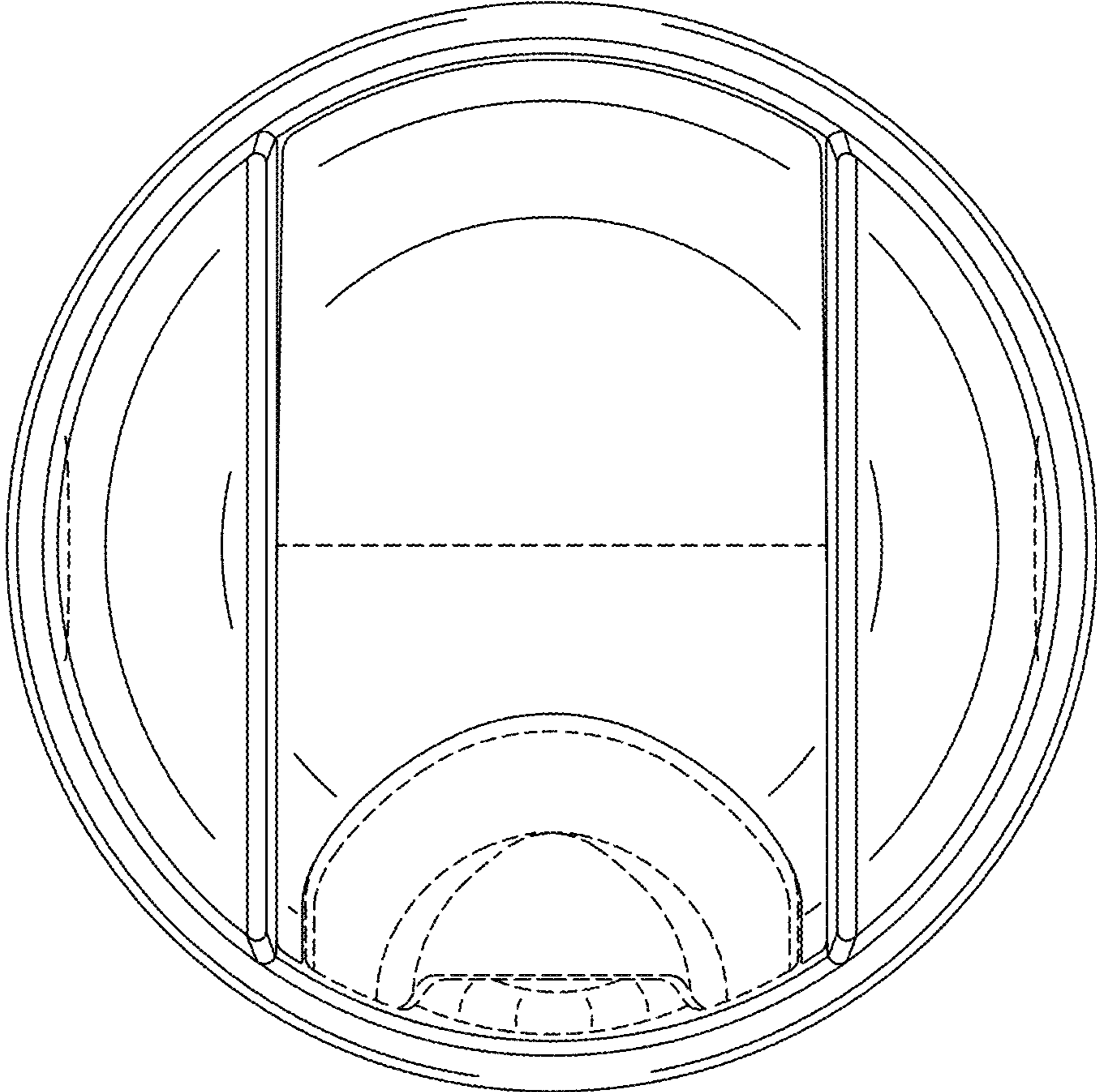


FIG. 6

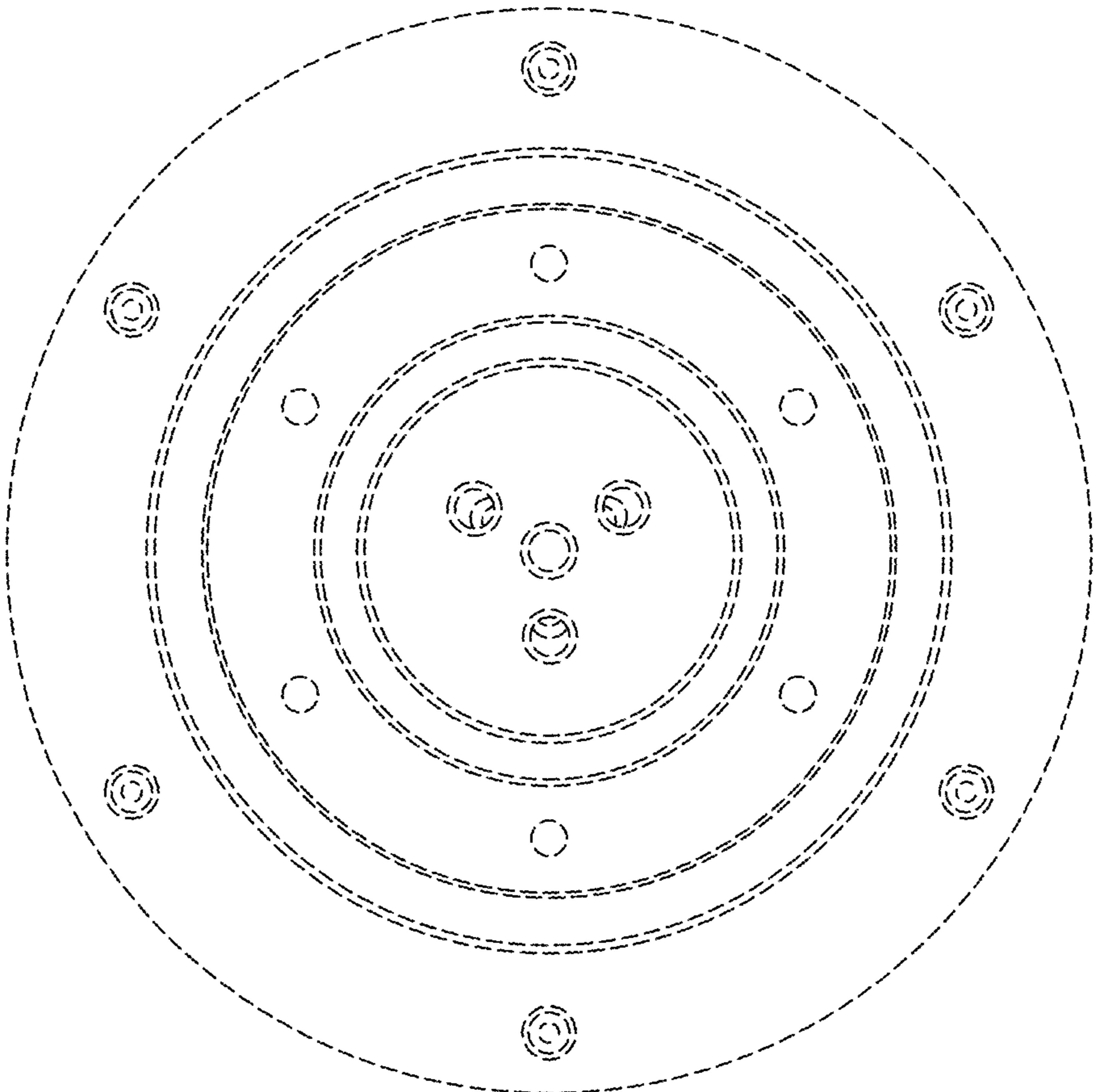


FIG. 7

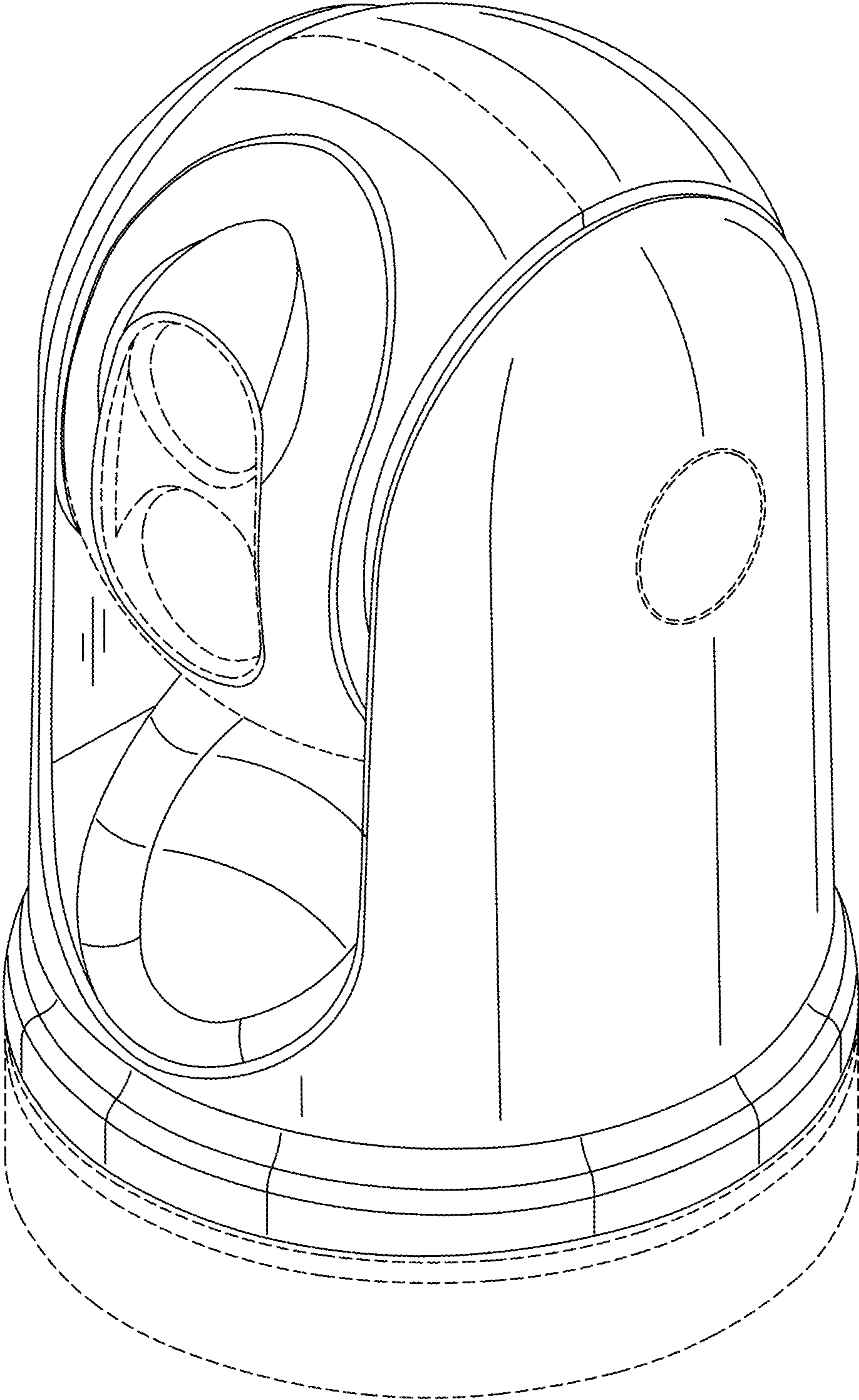


FIG. 8

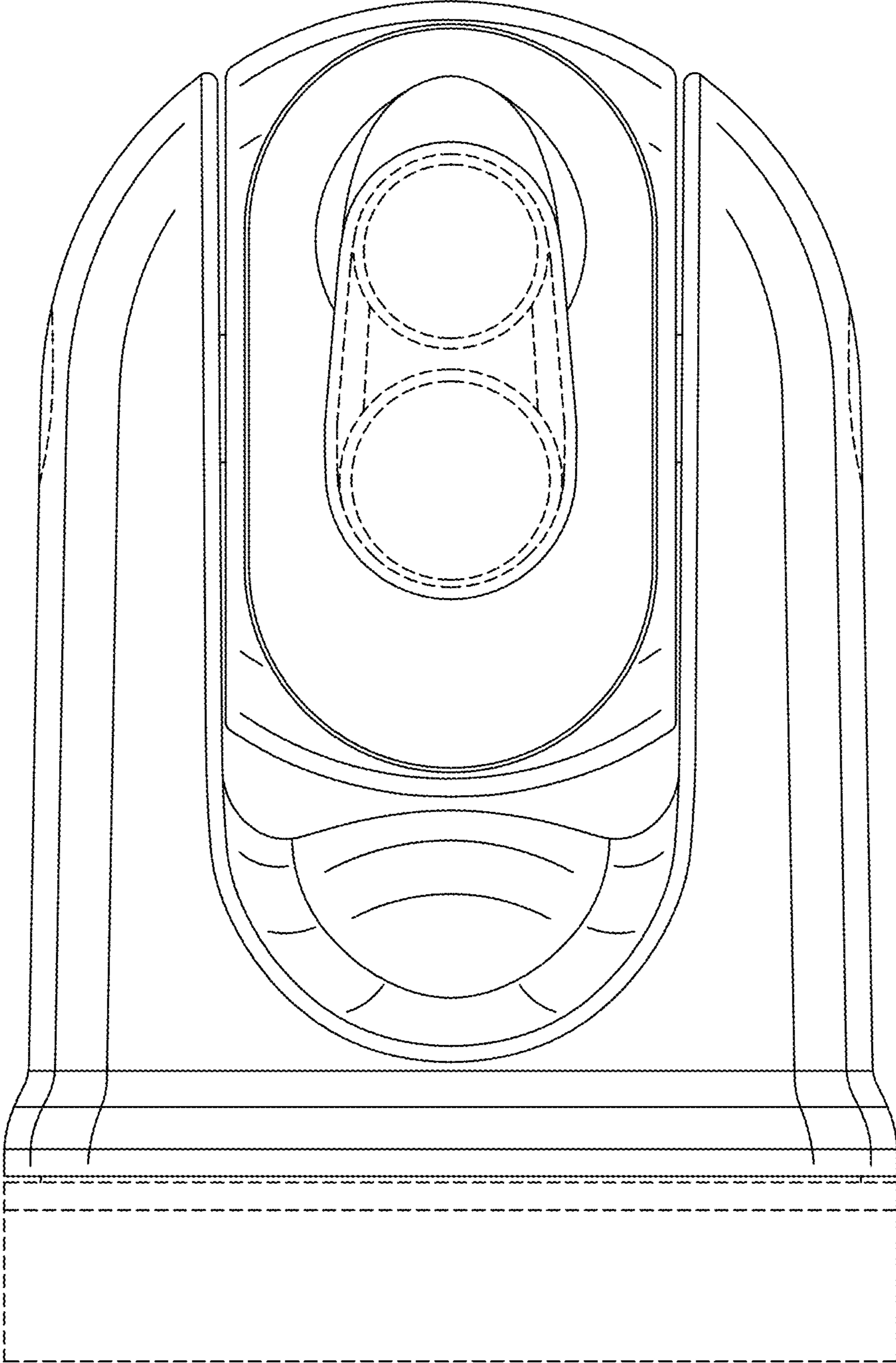


FIG. 9

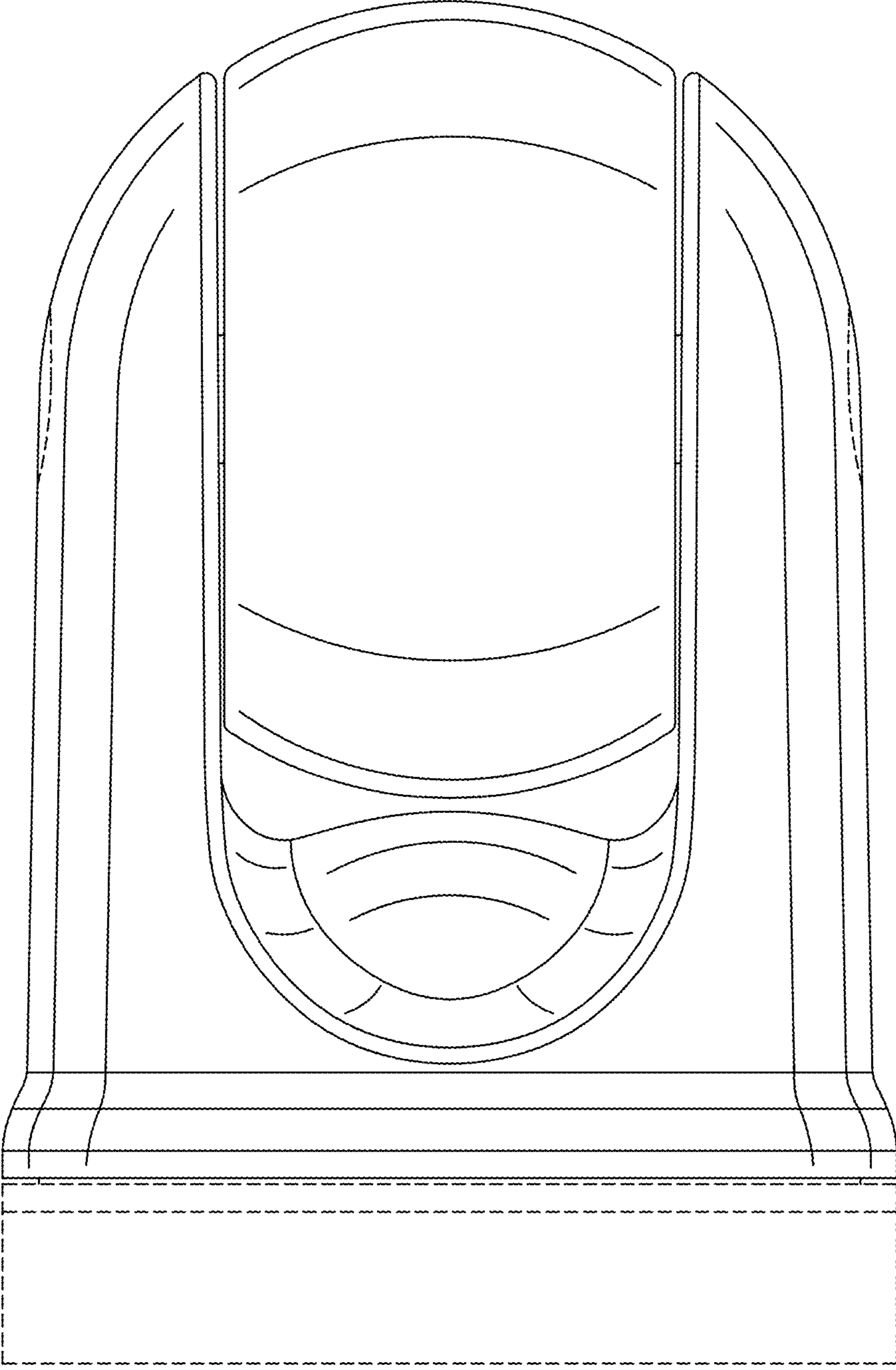


FIG. 10

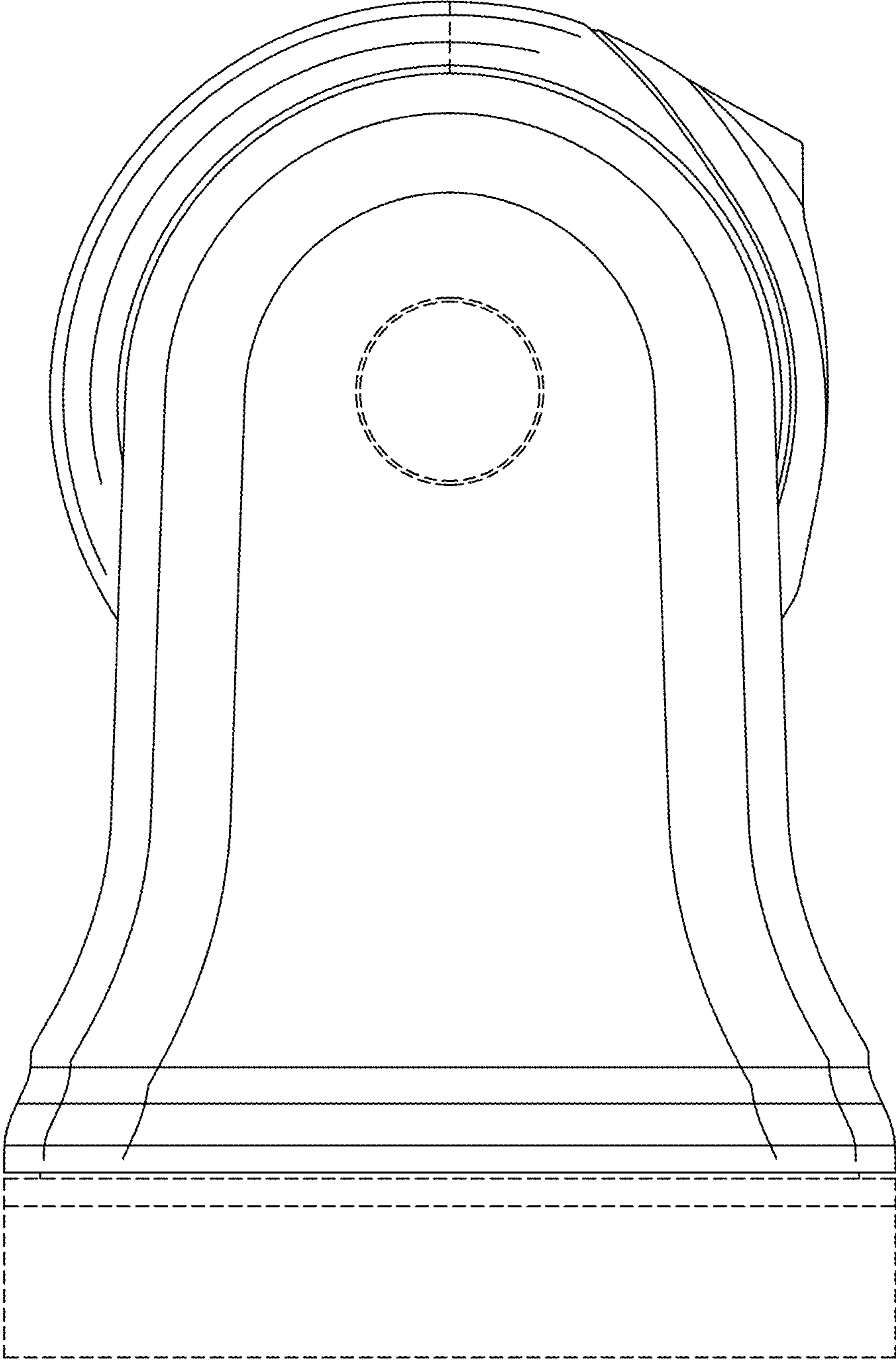


FIG. 11

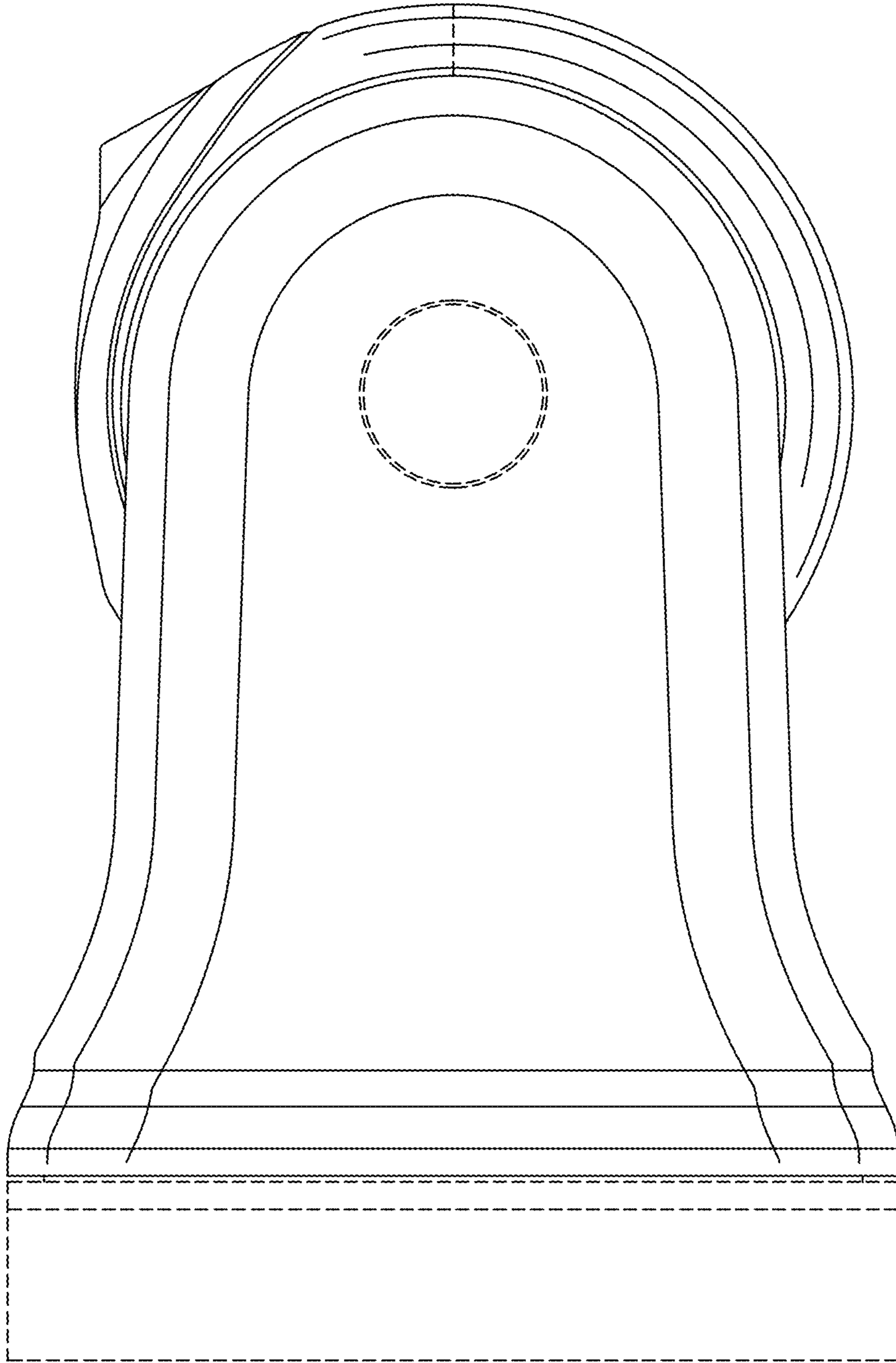


FIG. 12

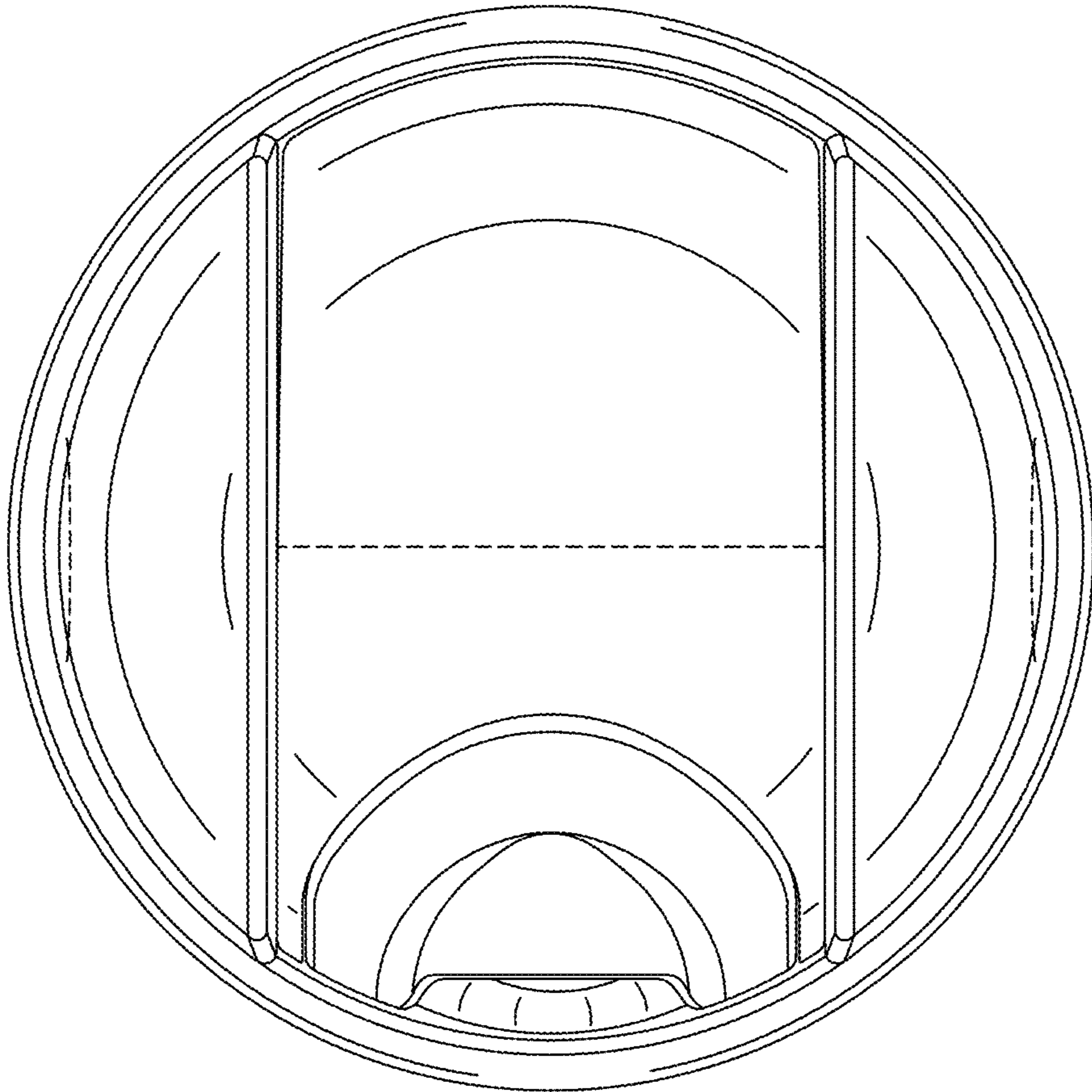


FIG. 13

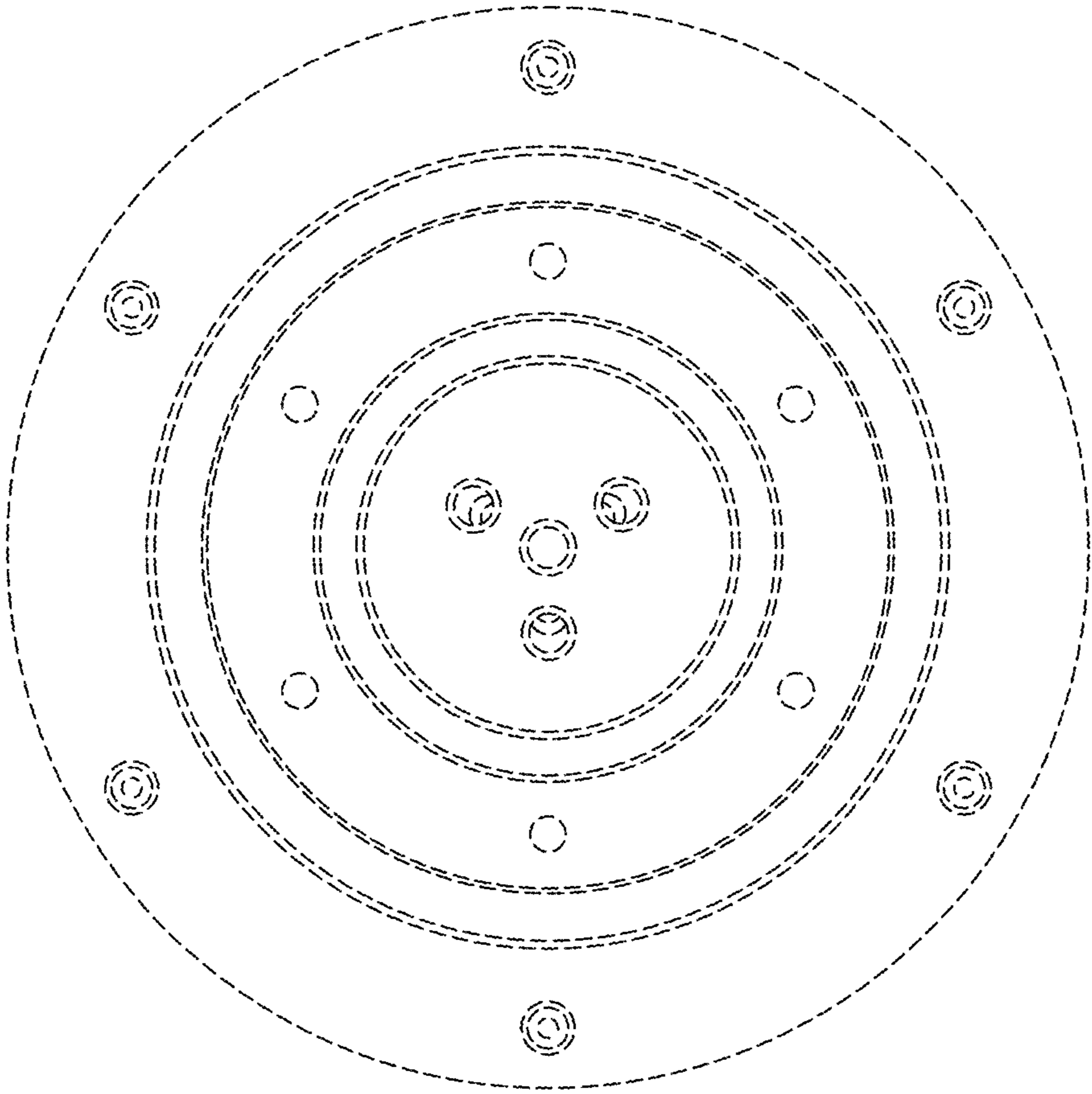


FIG. 14